



# Material Composition Declaration

## EPC2001

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	12.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	10.5319	85.60	87.55	855979
	Silicon oxide	7631-86-9	0.0406	0.33		3298
	Silicon nitride	12033-89-5	0.0126	0.10		1024
	Gallium nitride	25617-97-4	0.0494	0.40		4016
	Aluminum	7429-90-5	0.0835	0.68		6789
	Aluminum nitride	24304-00-5	0.0120	0.10		972
	Titanium	7440-32-6	0.0020	0.02		159
	Titanium nitride	25583-20-4	0.0071	0.06		579
	Copper	7440-50-8	0.0028	0.02		226
	Tungsten	7440-33-7	0.0022	0.02		183
	Polyimide		0.0285	0.23		2318
Under Bump Metal	Titanium	7440-32-6	0.0024	0.02	0.23	192
	Nickel	7440-02-0	0.0071	0.06		574
	Vanadium	7440-62-2	0.0004	0.00		29
	Copper	7440-50-8	0.0188	0.15		1529
Solder Bump	Tin	7440-31-5	1.4351	11.66	12.21	116635
	Silver	7440-22-4	0.0601	0.49		4885
	Copper	7440-50-8	0.0075	0.06		611
Sum in total:			12.3	100	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.